



PRODUCT INFORMATION LETTER

PIL MMS-MMY/14/8772
Dated 29 Oct 2014

LEAD FRAME MATERIAL CHANGE FOR UFDFPN8 AT CALAMBA

Sales Type/product family label	EEPROM assembled in UFDFPN8 2x3 mm at ST Calamba
Type of change	Package assembly material change
Reason for change	Lead frame material availability
Description	Lead frame material change from EFTEC-64 to C194
Forecasted date of implementation	22-Oct-2014
Forecasted date of samples for customer	22-Oct-2014
Forecasted date for STMicroelectronics change Qualification Plan results availability	22-Oct-2014
Involved ST facilities	Back-End

DOCUMENT APPROVAL

Name	Function
Leduc, Hubert	Marketing Manager
Rodrigues, Benoit	Product Manager
Pavano, Rita	Q.A. Manager



PRODUCT / PROCESS CHANGE INFORMATION

LEAD FRAME MATERIAL CHANGE FOR UFDFPN8 AT CALAMBA

What is the change?

UFDFPN8 (2x3 mm) at ST Calamba (Philippines) will be manufactured with new lead frame material **C194 Copper alloy** instead of current EFTEC-64 (no change on lead frame finishing, being NiPdAu).

Current EFTEC-64 lead frame material composition:

Cu: 99.17 to 99.36%

New C194 lead frame material composition:

Cu: 97% min

Fe: 2.5%

Why?

Production of current EFTEC-64 material was stopped.

When?

The production of the UFDFPN8 2x3 mm at ST Calamba with the new lead frame material C194 will start from date code Week 43 / 2014 (with a transition window between Week 43 and Week 47 before whole production shifts to frame with new material).

How will the change be qualified?

The frame with new material has been qualified using the standard ST Microelectronics Corporate Procedures for Quality & Reliability. QRMMY1429 will be available Week 44 / 2014.

What is the impact of the change?

- **Form:** no change
- **Fit:** no change
- **Function:** no change

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Appendix A- Product Change Information

Product family / Commercial products:	EEPROM assembled in UFDFPN8 2x3 mm at ST Calamba (Philippines)
Customer(s):	All
Type of change:	Package assembly material change
Reason for the change:	Lead frame material availability
Description of the change:	Lead frame material change from EFTEC-64 to C194
Forecast date of the change: (Notification to customer)	Week 43 / 2014
Forecast date of <u>Qualification samples</u> availability for customer(s):	N/A
Marking to identify the changed product:	N/A
Estimated date of first shipment:	Week 43 / 2014

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Document Revision History		
Date	Rev.	Description of the Revision
October 20, 2014	1.00	First draft creation

Source Documents & Reference Documents		
Source document Title	Rev.:	Date:

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